## INTEGRATED CIRCUITS

# DATA SHEET

**74LVC11**Triple 3-input AND gate

Product specification







74LVC11

#### **FEATURES**

- Wide supply voltage range of 1.2 V to 3.6 V
- In accordance with JEDEC standard no. 8-1A.
- Inputs accept voltages up to 5.5 V
- CMOS low power consumption
- Direct interface with TTL levels
- Output capability: standard
- I<sub>CC</sub> category: SSI

#### DESCRIPTION

The 74LVC11 is a high-performance, low power, low-voltage Si-gate CMOS device and superior to most advanced CMOS compatible

The 74LVC11 provides the 3-input AND function.

#### **QUICK REFERENCE DATA**

GND = 0 V;  $T_{amb}$  = 25°C;  $t_{f}$  =  $t_{f}$   $\leq$  2.5 ns

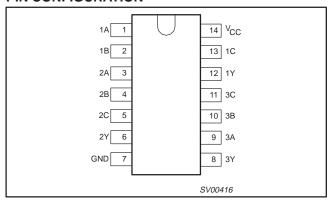
SYMBOL	PARAMETER	CONDITIONS	TYPICAL	UNIT
t <sub>PHL</sub> /t <sub>PLH</sub>	Propagation delay nA, nB, nC to nY	$C_L = 50 \text{ pF};$ $V_{CC} = 3.3 \text{ V}$	3.7	ns
C <sub>I</sub>	Input capacitance		5.0	pF
C <sub>PD</sub>	Power dissipation capacitance per gate	Notes 1 and 2	26	pF

- 1.  $C_{PD}$  is used to determine the dynamic power dissipation ( $P_D$  in  $\mu W$ )  $P_D$  is used to determine the dynamic power dissipation ( $P_D$  if  $P_D = C_{PD} \times V_{CC}^2 \times f_i + \sum (C_L \times V_{CC}^2 \times f_o)$  where:  $f_i$  = input frequency in MHz;  $C_L$  = output load capacity in pF;  $f_0$  = output frequency in MHz;  $V_{CC}$  = supply voltage in V;  $\sum (C_L \times V_{CC}^2 \times f_o)$  = sum of the outputs.
- 2. The condition is  $V_I = GND$  to  $V_{CC}$ .

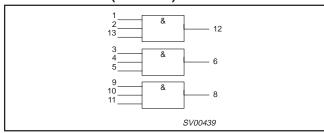
#### **ORDERING INFORMATION**

PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	DWG NUMBER
14-Pin Plastic SO	-40°C to +85°C	74LVC11 D	74LVC11 D	SOT108-1
14-Pin Plastic SSOP Type II	-40°C to +85°C	74LVC11 DB	74LVC11 DB	SOT337-1
14-Pin Plastic TSSOP Type I	-40°C to +85°C	74LVC11 PW	74LVC11PW DH	SOT402-1

#### **PIN CONFIGURATION**



#### LOGIC SYMBOL (IEEE/IEC)



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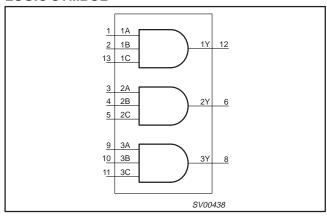
## Triple 3-input AND gate

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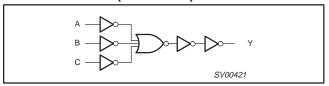
#### **PIN DESCRIPTION**

PIN NUMBER	SYMBOL	NAME AND FUNCTION
1, 3, 9	1A – 3A	Data inputs
2, 4, 10	1B – 3B	Data inputs
7	GND	Ground (0 V)
12, 6, 8	1Y – 3Y	Data outputs
13, 5, 11	1C – 3C	Data inputs
14	V <sub>CC</sub>	Positive supply voltage

#### **LOGIC SYMBOL**



### **LOGIC DIAGRAM (ONE GATE)**



#### **FUNCTION TABLE**

	INPUTS		OUTPUTS
nA	nB	nC	nY
L	L	L	L
L	L	Н	L
L	Н	L	L
L	Н	Н	L
Н	L	L	L
н	L	Н	L
Н	Н	L	L
Н	Н	Н	Н

#### NOTES:

H = HIGH voltage level L = LOW voltage level

#### **RECOMMENDED OPERATING CONDITIONS**

SYMBOL	PARAMETER	CONDITIONS	LIM	UNIT	
STWIBOL	FARAMETER	CONDITIONS	MIN	MAX	ONII
V <sub>CC</sub>	DC supply voltage (for max. speed performance)		2.7	3.6	V
V <sub>CC</sub>	DC supply voltage (for low-voltage applications)		1.2	3.6	V
VI	DC input voltage range		0	5.5	V
Vo	DC output voltage range		0	V <sub>CC</sub>	V
T <sub>amb</sub>	Operating free-air temperature range		-40	+85	°C
t <sub>r</sub> , t <sub>f</sub>	Input rise and fall times	$V_{CC} = 1.2 \text{ to } 2.7V$ $V_{CC} = 2.7 \text{ to } 3.6V$	0 0	20 10	ns/V

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#### ABSOLUTE MAXIMUM RATINGS<sup>1</sup>

In accordance with the Absolute Maximum Rating System (IEC 134) Voltages are referenced to GND (ground = 0V)

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V <sub>CC</sub>	DC supply voltage		-0.5 to +6.5	V
I <sub>IK</sub>	DC input diode current	$V_I < 0$	-50	mA
VI	DC input voltage	Note 2	-0.5 to +5.5	V
I <sub>OK</sub>	DC output diode current	$V_{O} > V_{CC}$ or $V_{O} < 0$	±50	mA
Vo	DC output voltage	Note 2	-0.5 to V <sub>CC</sub> +0.5	V
I <sub>O</sub>	DC output source or sink current	$V_{O} = 0$ to $V_{CC}$	±50	mA
I <sub>GND</sub> , I <sub>CC</sub>	DC V <sub>CC</sub> or GND current		±100	mA
T <sub>stg</sub>	Storage temperature range		-65 to +150	°C
P <sub>TOT</sub>	Power dissipation per package  – plastic mini-pack (SO)  – plastic shrink mini-pack (SSOP and TSSOP)	above +70°C derate linearly with 8 mW/K above +60°C derate linearly with 5.5 mW/K	500 500	mW

#### NOTES:

#### DC ELECTRICAL CHARACTERISTICS

Over recommended operating conditions voltages are referenced to GND (ground = 0V)

			ι	LIMITS		
SYMBOL	PARAMETER	TEST CONDITIONS	Temp = -	UNIT		
			MIN	TYP <sup>1</sup>	MAX	1
.,	LHCH lavel land value	V <sub>CC</sub> = 1.2V	V <sub>CC</sub>			V
V <sub>IH</sub>	HIGH level Input voltage	V <sub>CC</sub> = 2.7 to 3.6V	2.0			1 <sup>v</sup>
	L OW love leave to the ma	V <sub>CC</sub> = 1.2V			GND	V
$V_{IL}$	LOW level Input voltage	V <sub>CC</sub> = 2.7 to 3.6V			0.8	1 <sup>v</sup>
		$V_{CC} = 2.7V$ ; $V_I = V_{IH}$ or $V_{IL}$ ; $I_O = -12mA$	V <sub>CC</sub> -0.5			
	LUCLIand autout valtage	$V_{CC} = 3.0V; V_I = V_{IH} \text{ or } V_{IL}; I_O = -100\mu\text{A}$	V <sub>CC</sub> -0.2	V <sub>CC</sub>		
V <sub>OH</sub>	HIGH level output voltage	$V_{CC} = 3.0V; V_I = V_{IH} \text{ or } V_{IL}; I_O = -12\text{mA}$	V <sub>CC</sub> -0.6			]
		$V_{CC} = 3.0V$ ; $V_I = V_{IH}$ or $V_{IL}$ ; $I_O = -24$ mA	V <sub>CC</sub> - 1.0			
		$V_{CC} = 2.7V$ ; $V_I = V_{IH}$ or $V_{IL}$ ; $I_O = 12mA$			0.40	
$V_{OL}$	LOW level output voltage	$V_{CC} = 3.0V; V_I = V_{IH} \text{ or } V_{IL}; I_O = 100 \mu A$		GND	0.20	V
		$V_{CC} = 3.0V$ ; $V_I = V_{IH}$ or $V_{IL}$ ; $I_O = 24mA$			0.55	1
t <sub>l</sub>	Input leakage current	V <sub>CC</sub> = 3.6V; V <sub>I</sub> = 5.5V or GND		±0.1	±5	μΑ
I <sub>CC</sub>	Quiescent supply current	$V_{CC} = 3.6V$ ; $V_I = V_{CC}$ or GND; $I_O = 0$		0.1	10	μΑ
Δl <sub>CC</sub>	Additional quiescent supply current per input pin	$V_{CC} = 2.7V$ to 3.6V; $V_I = V_{CC} - 0.6V$ ; $I_O = 0$		5	500	μА

#### NOTE:

<sup>1.</sup> Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

<sup>2.</sup> The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

<sup>1.</sup> All typical values are at  $V_{CC}$  = 3.3V and  $T_{amb}$  = 25°C.

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#### **AC CHARACTERISTICS**

GND = 0 V;  $t_r$  =  $t_f \leq$  2.5 ns;  $C_L$  = 50 pF;  $R_L$  = 500 $\Omega$ ;  $T_{amb}$  = -40°C to +85°C

SYMBOL	PARAMETER	WAVEFORM	V <sub>C</sub>	$_{\rm C}$ = 3.3V ±0	.3V	V <sub>CC</sub> =	UNIT	
			MIN	TYP <sup>1</sup>	MAX	MIN	MAX	
t <sub>PHL</sub> /t <sub>PLH</sub>	Propagation delay nA, nB, nC to nY	1, 2	-	3.7	6.2	_	7.0	ns

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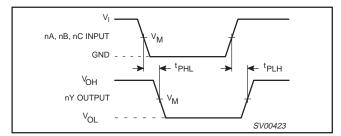
#### NOTE:

1. These typical values are at  $V_{CC} = 3.3V$  and  $T_{amb} = 25$ °C.

#### **AC WAVEFORMS**

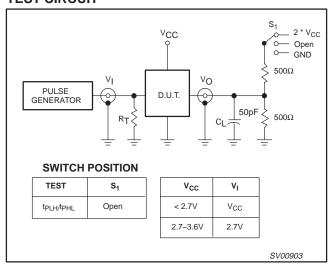
$$\begin{split} V_M &= 1.5 \text{ V at V}_{CC} \geq 2.7 \text{ V} \\ V_M &= 0.5 \bullet V_{CC} \text{ at V}_{CC} < 2.7 \text{ V} \end{split}$$

 $V_{OL}$  and  $V_{OH}$  are the typical output voltage drop that occur with the output load.



Waveform 1. Input (nA, nB, nC) to output (nY) propagation delays.

#### **TEST CIRCUIT**

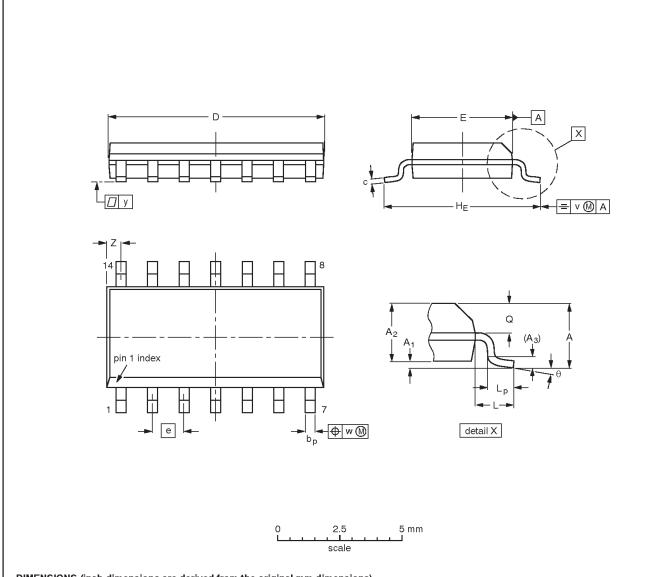


Waveform 2. Load circuitry for switching times.

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#### SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1



#### DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	А3	bp	С	D <sup>(1)</sup>	E <sup>(1)</sup>	е	HE	L	Lp	Q	v	w	у	Z <sup>(1)</sup>	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	8.75 8.55	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8°
inches	0.069	0.010 0.004	0.057 0.049	0.01		0.0100 0.0075		0.16 0.15	0.050	0.244 0.228	0.041	0.039 0.016		0.01	0.01	0.004	0.028 0.012	O°

#### Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

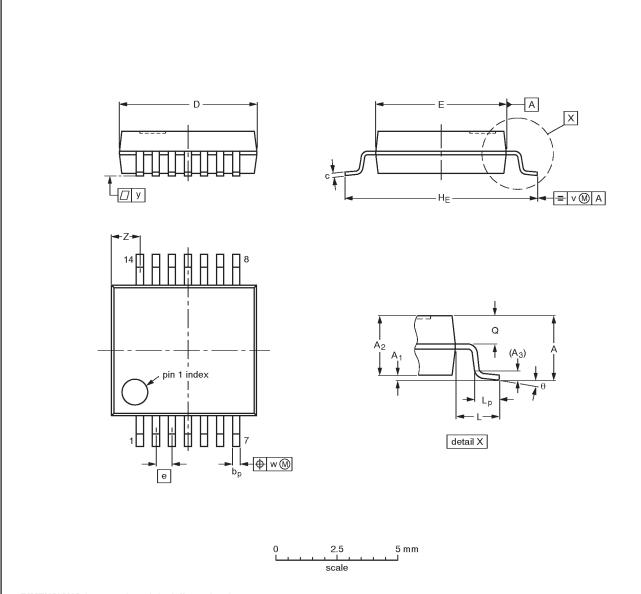
OUTLINE		REFER	RENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE
SOT108-1	076E06S	MS-012AB			<del>95-01-23</del> 97-05-22

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## SSOP14: plastic shrink small outline package; 14 leads; body width 5.3 mm

SOT337-1



#### DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	<b>A</b> <sub>3</sub>	bp	c	D <sup>(1)</sup>	E <sup>(1)</sup>	е	HE	L	Lp	Ø	٧	w	у	Z <sup>(1)</sup>	θ
mm	2.0	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	6.4 6.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	1.4 0.9	8° 0°

#### Note

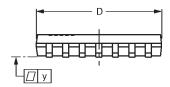
1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

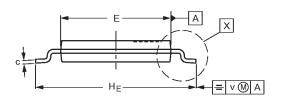
OUTLINE		EUROPEAN	ISSUE DATE				
VERSION	IEC	IEC JEDEC EIAJ				1930E DATE	
SOT337-1		MO-150AB				<del>95-02-04</del> 96-01-18	

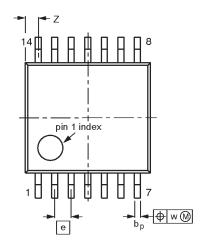
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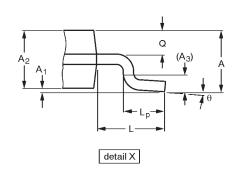
TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm

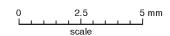
SOT402-1











#### DIMENSIONS (mm are the original dimensions)

UNIT	A max.	Α1	A <sub>2</sub>	A <sub>3</sub>	bр	c	D <sup>(1)</sup>	E <sup>(2)</sup>	е	HE	L	Lp	Q	v	w	у	Z <sup>(1)</sup>	θ
mm	1.10	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	5.1 4.9	4.5 4.3	0.65	6.6 6.2	1.0	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.72 0.38	8° 0°

#### Notes

- 1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
- 2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	RENCES	EUROPEAN	ISSUE DATE	ĺ
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE	ĺ
SOT402-1		MO-153			<del>-94-07-12</del> 95-04-04	

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**NOTES** 

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#### Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
Preliminary specification	Qualification	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make chages at any time without notice in order to improve design and supply the best possible product.
Product specification	Production	This data sheet contains final specifications. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.

<sup>[1]</sup> Please consult the most recently issued datasheet before initiating or completing a design.

#### **Definitions**

**Short-form specification** — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

**Limiting values definition** — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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print code Date of release: 08-98

Document order number: 9397-750-04483

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